#### **FEE TRANSMITTAL**

#### Electronic Version v08

# Stylesheet Version v08.0

Title of Invention

[METHOD OF FABRICATING FLIP CHIP BALL GRID ARRAY PACKAGE]

Application Number:

Date:

First Named Applicant: Mr. Meng-Jen Wang

Attorney Docket Number: 11182-US-PA

# **TOTAL FEE AUTHORIZED \$810**

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

#### BASIC FILING FEE

Fee Description	Fee Code	Amount \$	Fee Paid \$				
Utility Filing Fee	1001	770	770				
Subtotal For Basic Filing Fees: \$ 770							

## **EXTRA CLAIM FEES**

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$		
Total Claims: 7	0	1202	18	0		
Independent Claims : 1	0	1201	86	0		
Subtotal For Extra Claims Fees: \$ (						

## **ASSIGNMENT FEES**

Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$		
Recording Each Patent	00000000	1	8021	40	40		
Assignment Per Property Fee							
Subtotal For Additional Fees: \$40							

#### **AUTHORIZED BILLING INFORMATION**

The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:

Credit account number: 1000

Expiration Date (YYYYMMDD): 2006-10-31

Authorized name: LEE, HUAI-LU

Billing address: 99999